CLAIMS

1. A method of repairing a pedestal surface, comprising the step of polishing said surface using a coarse surface of a film.

2. A method according to claim 1, wherein the film has a coarseness of from 1 to 45 microns.

3. A method of repairing a pedestal surface, comprising the step of polishing said surface using a coarse surface with a coarseness of from 1 to 45 microns.

4. A method according to claim 3, wherein the coarse surface is a coarse surface of a film.

5. A method according to any one to claims 1, 2 and 4, wherein the film is mounted on one side of a silicon wafer.

6. A method according to claim 5, wherein the film is mounted on the silicon wafer using a mineral oil as an adhesive.

7. A method according to claim 6, wherein the mineral oil is a fluorinated oil

8. A method according to any one of claims 5 to 7, wherein the other side of the silicon wafer from the coarse surface has tape thereon to provide an improved grip.

9. A method according to any one to preceding claims, further comprising the step of applying IPA between the coarse surface and the pedestal surface prior to polishing.

10. A method according to any one to preceding claims, wherein the coarse surface comprises diamond grains.

11. A method according to any one to preceding claims, wherein the pedestal is a heater pedestal.

12. A method according to any one to preceding claims, wherein the pedestal is a pedestal for use in CVD, PVD, metal / oxide etching, photolithographic scanning or semiconductor processing that requires heating or a vacuum or mechanical devices to secure the position of a wafer to the pedestal surface.

13. A pedestal repaired according to the method of any one of the preceding claims.

14. A pedestal repair apparatus comprising a silicon wafer, with a coarse film on one side thereof.